

IN THE CLAIMS

Claim 1 (currently amended). A method of producing a pressure-sensitive adhesive article having at least one layer of a thermally conductive pressure-sensitive adhesive, ~~characterized in that wherein~~ a layer of ~~the a~~ thermally conductive pressure-sensitive adhesive that is anisotropic at least in respect of one property is produced in a coating process by stretching, drawing or compressing, said layer possessing in at least one direction along the plane of the layer a shrinkback of at least 3% in respect of the longitudinal extent of the layer, measured on the free pressure-sensitive adhesive ~~film layer~~.

Claim 2 (currently amended). The method of claim 1, ~~characterized in that wherein~~ the coating process is a hotmelt roll coating process, a melt diecoating process or an extrusion coating process.

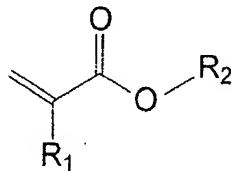
Claim 3 (currently amended). The method of claim 1, ~~characterized in that wherein~~ the coating process ~~is a conventional coating process with subsequent comprises~~ stretching or drawing on a stretchable carrier.

Claim 4 (currently amended). The method of ~~any one of claims 1 to 3, characterized in that claim 1, wherein~~ the thermally conductive pressure-sensitive adhesive is coated onto one or both sides of a ~~sheetlike or tapelike~~ carrier.
~~The method of claim 4, characterized in that the carrier is a transfer tape, a release liner or a thermally conducting carrier material.~~

Claim 5 (new). The method of claim 4, wherein the carrier is a transfer tape, a release liner or a thermally conducting carrier material.

Claim 6 (currently amended). The method of ~~any one of claims 1 to 5, characterized in that claim 1, wherein~~ the pressure-sensitive adhesive ~~used~~ is based on polyacrylate and/or polymethacrylate.

Claim 7 (currently amended). The method of claim 6, ~~characterized in that wherein~~ the pressure-sensitive adhesive is based to an extent of at least 50% by weight on at least one acrylic monomer selected from the group consisting of the compounds of the following general formula:



where $\text{R}_1 = \text{H}$ or CH_3 and the radical $\text{R}_2 = \text{H}$ or CH_3 or is ~~chosen~~ selected from the group consisting of the branched or unbranched, saturated alkyl groups having 2 – 30 carbon atoms and the average molecular weight M_w of the pressure-sensitive adhesive is at least 200 000 g/mol.

Claim 8 (currently amended). The method of ~~any one of claims 1 to 6, characterized in that claim 1, wherein the pressure-sensitive adhesive comprises~~ crosslinkers, ~~especially difunctional or polyfunctional acrylates and/or methacrylates, difunctional or polyfunctional isocyanates or difunctional or polyfunctional epoxides, have been added to the pressure-sensitive adhesive.~~

Claim 9 (currently amended). The method of claim 8, ~~characterized in that wherein~~ the pressure-sensitive adhesive is crosslinked, ~~preferably photochemically~~, immediately after or during hotmelt coating.

Claim 10 (currently amended). The method of ~~any one of claims 1 to 9, characterized in that claim 1, wherein~~ thermally conductive materials, ~~especially metallic or ceramic materials, graphite, aluminum, aluminum oxide, aluminum nitride, titanium dioxide, titanium boride, silicon nitride, carbonitride or boron nitride, preferably in powder form are added to said pressure-sensitive adhesive.~~

Claim 11 (currently amended). The method of claim 10, ~~characterized in that wherein~~ the thermally conductive materials are admixed added in a fraction an amount of from 5% to

200% by weight, ~~preferably between 6% and 50% by weight, based on the weight of the pressure-sensitive adhesive.~~

Claim 12 (currently amended). The method of ~~any one of claims 1 to 11, characterized in claim 1~~ that the thermal conductivity of the pressure-sensitive adhesive is at least 0.05 W/mK.

Claim 13 (currently amended). The method of ~~any one of claims 1 to 12, characterized in that claim 1, wherein~~ the thermal conductivity is anisotropic and is lower along a plane lying in the pressure-sensitive adhesive layer than transverse to the plane of the layer, it being at least 0.06 W/mK in a direction transverse to the plane of the layer.

Claim 14 (currently amended). The method of ~~any one of claims 1 to 13, characterized in that claim 1, wherein~~ the pressure-sensitive adhesive comprises further substances or additives, ~~such as selected from the group consisting of~~ aging inhibitors, light stabilizers, ozone protectants, fatty acids, plasticizers, nucleators, expandants, accelerators and/or fillers.

Claim 15 (currently amended). A pressure-sensitive adhesive article, ~~in particular~~ for bonding two electrical parts, ~~obtainable obtained~~ by a ~~the~~ method of ~~any one of claims 1 to 14~~ claim 1.

Claim 16 (currently amended). The pressure-sensitive adhesive article of claim 15 in the form of a diecut.

Claim 17 (new). The method of claim 8, wherein said crosslinkers are selected from the group consisting of difunctional or polyfunctional acrylates and/or methacrylates, difunctional or polyfunctional isocyanates and difunctional or polyfunctional epoxides.

Claim 18 (new). The method of claim 10 wherein said thermally conductive materials are selected from the group consisting of metallic or ceramic materials, graphite, aluminum, aluminum oxide, aluminum nitride, titanium dioxide, titanium boride, silicon nitride, carbonitride and boron nitride.

Claim 19 (new). The method of claim 18, wherein said thermally conductive materials are in powder form.

Claim 20 (new). The method of claim 11, wherein said amount is between 6% and 50% by weight.